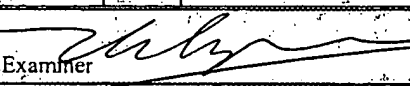


<b>APPLICANT'S ART CITATION</b> (Use several sheets if necessary)		Application <b>Not Yet Known</b>		OFGS File No. <b>IR-2229 (2-3620)</b>			
		Applicant <b>Srikant SRIDEVAN</b>					
		Filing Date <b>Herewith</b>		Group Art Unit <b>__</b>			
<b>U.S. PATENT DOCUMENTS</b>							
Examiner Initial	Document Number	Date MM-YYYY	Name	Class	Sub-class	Filing Date If Appropriate	
TTN	US-5,589,695	12-1996	Malhi	257	77		
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TTN	US-2002/0149021	10-2002	Casady et al.	257	77		
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	US-						
<b>FOREIGN PATENT DOCUMENTS</b>							
	Document Number	Date MM-YYYY	Country	Class	Sub-class	Translation	
						Yes	No
<b>OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
TTN	1.	"Application Example 2: Flyback Power Supply Operating from > 600 V DC," <a href="http://www.siced.de/en/example_2.html">http://www.siced.de/en/example_2.html</a> , 1 page, downloaded October 28, 2003.					
TTN	2.	"Silicon carbide moves further towards commercialization," <a href="http://www.compoundsemiconductor.net/magazine/article/8/1/7/1">http://www.compoundsemiconductor.net/magazine/article/8/1/7/1</a> , 4 pages, downloaded October 28, 2003.					
TTN	3.	Philip G. Neudeck, "SiC Technology," NASA Lewis Research Center, 54 pages (1998).					
TTN	4.	Werner Tursky, "Devices and their Packaging Technology," pages 1-6, IEEE-4th Workshop Future of Electronic Power Processing and Conversion, May 27-29, 2001, Salina, Italy.					
Examiner 		Date Considered <u>1/28/2005</u>					
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.							